Product Change Notification

113999 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**113999 - 00**
Change Title:	**Intel® RAID Expander RES3FV288 & RES3TV360, PCN 113999-00,** **Product Material** **Pb-free bump conversion for Intel® expanders**
Date of Publication:	**August 25, 2015**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	September 9, 2015

* *Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel is implementing the following change on the Intel® RAID Expander RES3FV288 & RES3TV360:

In order to align with the RoHS requirements, Intel is transitioning the lead-containing bumps currently used on Intel® expanders RES3FV288 and RES3TV360 to lead-free bumps, in anticipation of the exemption termination for the leader bumps in FCBGA products in 2016. The external solder ball types will not change.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers, but encourages customers to understand the changes and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
RES3FV288	932895	H19567-004	H19570-153	H19567-005	H19570-154
RES3TV360	932894	H19563-004	H19565-153	H19563-005	H19565-154

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
August 25, 2015	00	Originally Published PCN